


PRESS RELEASE


Schurter Spotlights First IEC Compliant Chip Fuse

Series USI 1206 is smallest Universal Module Fuse (UMF) with 1206 Footprint

Lucerne - June 27, 2006 - SCHURTER released today the first IEC chip fuse series USI 1206, Universal Modular Fuse (UMF) . The USI 1206 offers quick-acting characteristic (F) according to IEC 60127-4 with rated current values up to 6.3 A. It boasts high melting I^2t values, which provides greater withstand against high inrush or pulse currents.

Current ratings range from 0.5 to 6.3 A with voltage ratings of 63 VDC and 32 VAC. The device provides a breaking capacity of 63 A at rated voltages and an operating temperature range of -55°C to +90°C.

The fuse is designed to provide secondary overcurrent protection in power inverters, low-voltage power supplies, integrated display and storage subsystems as well as in portable medical devices and sensor-rich in-car electronics. Providing optimal performance in an extremely small package size 1206 (3.2 mm by 1.6 mm by 0.6 mm).

SCHURTER's advanced thin film technology process yields very predictable and stable performance results. Each fuse passes through the testing procedure in order to qualify for use in the most sensitive electronic systems. The legend marking on each fuse allows a clear visual identification. The fuse is approved according to IEC 60127-4/2  and carries cURus, METI and CCC approvals. It is the first 1206 fuse to obtain METI approval.

The device supports lead (Pb)-free soldering in reflow, or vapor phase processes and is RoHS compliant according to the EU-Directive 2002/95/EG. It is supplied on tape either with 1k or 5k or 15k pieces.